Fourth Quarter FY 2012 Roadshow and Webcast

hosted by Bank of America Merrill Lynch London, 20 – 21 November 2012



Ulrich Pelzer Corporate Vice President Finance, Treasury & Investor Relations



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■ Infineon at a Glance

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Disclaimer:

This presentation contains forward-looking statements about the business, financial condition and earnings performance of the Infineon Group.

These statements are based on assumptions and projections resting upon currently available information and present estimates. They are subject to a multitude of uncertainties and risks. Actual business development may therefore differ materially from what has been expected.

Beyond disclosure requirements stipulated by law, Infineon does not undertake any obligation to update forward-looking statements.

Revenue Split by Division



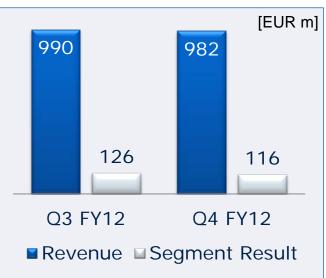
Q4 FY 2012 revenue: EUR 982m



Decreasing Segment Result Margin due to High Investments







[EUR m]	Q3 FY12	Q4 FY12	FY 2012
Revenue	990	982	3,904
Segment Result	126	116	527
SR Margin	12.7%	11.8%	13.5%
Net Income*	82	138	427
Investment	158	246	890
FCF from cont. operations	-22	47	-219
Gross Cash	2,150	2,235	2,235
Net Cash	1,907	1,940	1,940

^{*} Net Income includes "income from discontinued operations, net of income taxes" in Q3 FY12 EUR -8m, in Q4 FY12 EUR 9m and in FY 2012 EUR-5m. Net Income in Q4 FY12 includes income tax benefits of EUR 52m.

Tight Customer Relationships are Based on System Know-how and App Understanding



ATV



IPC



PMM



CCS



Distributors







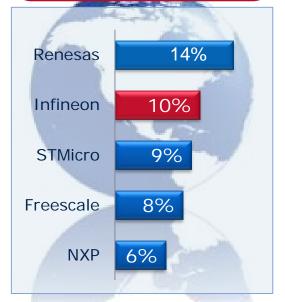


Infineon Holds Top Positions in All Target Markets



Automotive

#2

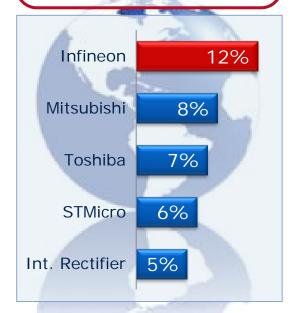


Calendar year 2011.

Source: Strategy Analytics, April 2012.

Power

#1

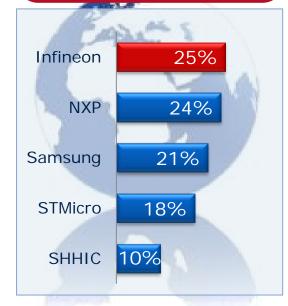


Calendar year 2011.

Source: IMS Research (an IHS company), July 2012.

Chip Card

#1



Calendar year 2011.

Source: IMS Research (an IHS company), August 2012.

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New Era: Multiple Factors Driving Demand for Power Semiconductors



'90 - '10

'10 - '30







Electrification of powertrain fuels demand for high-power semis in cars and doubles silicon content.





Shift towards renewable energies requires orders of magnitude more high-power semis per MW of power generated.





Higher efficiency in power conversion lowers CO₂, material and electricity costs.

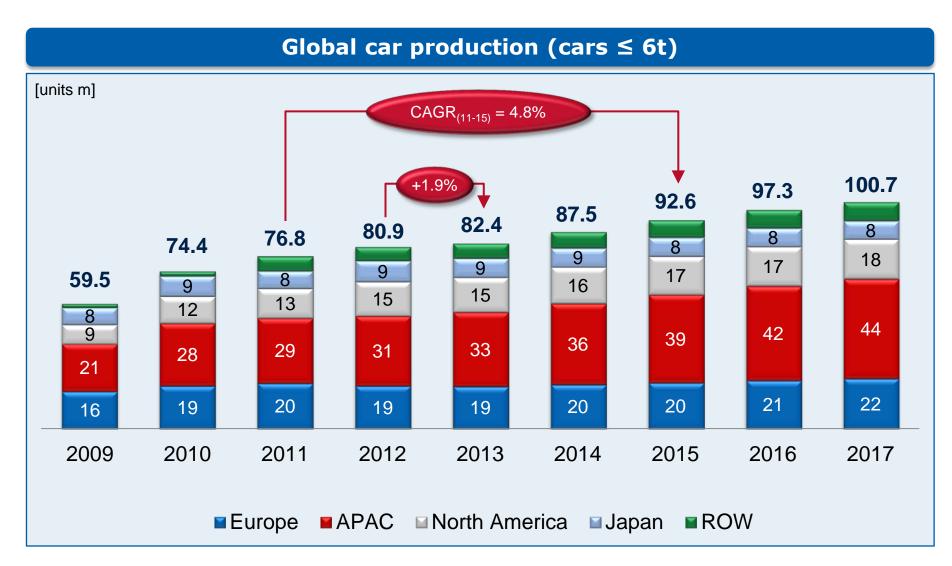




Stronger demand for goods containing power semis due to faster increase in standard of living in BRIC countries.

Despite Near-Term Outlook Cuts, Long-Term Prospect Still Healthy

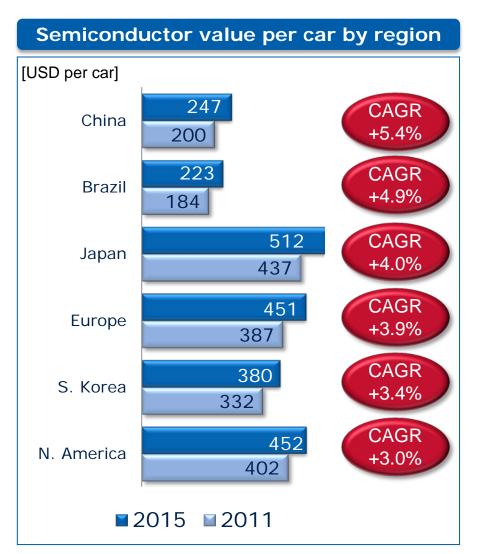


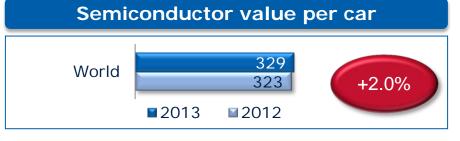


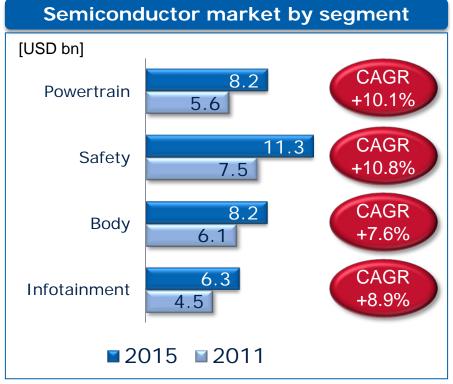
Source: IHS, October 2012.

Rising Semiconductor Value Per Car Drives Market





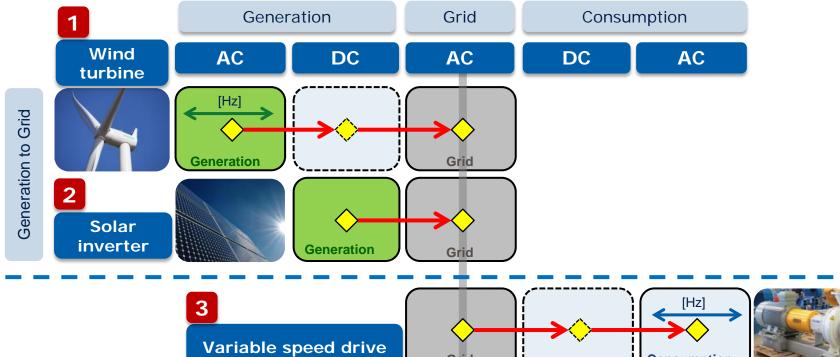




Source: Strategy Analytics, October 2012; including semiconductor sensors.

Every Electricity Conversion Step Requires Infineon Components





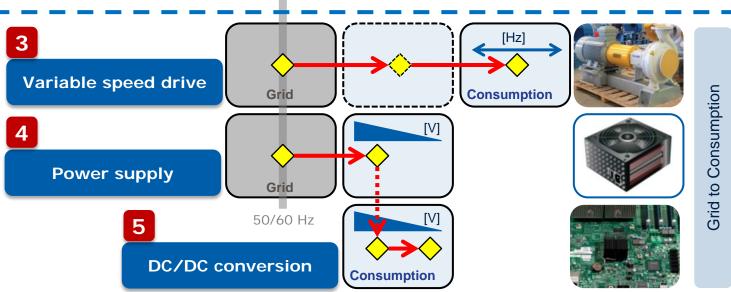


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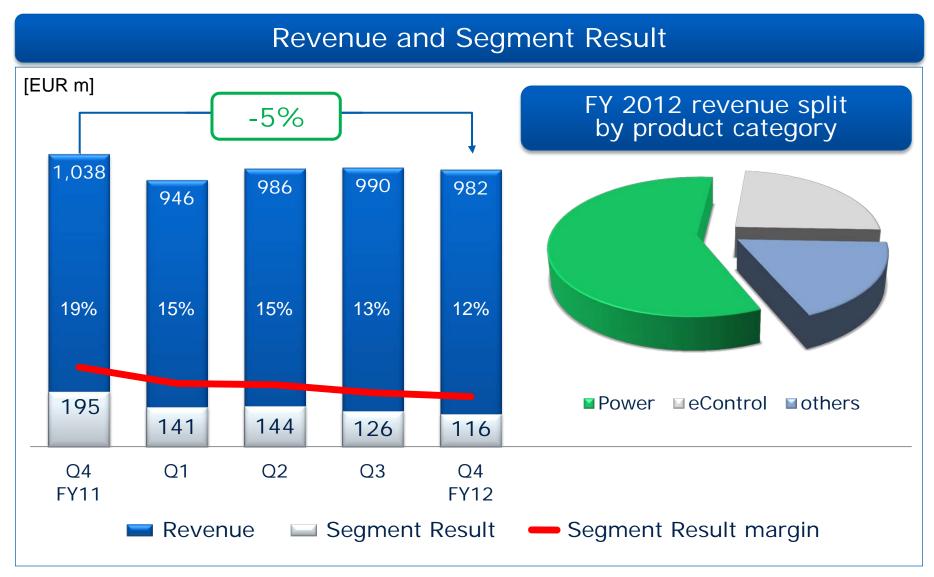
■ Infineon at a Glance

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■ Results and Outlook

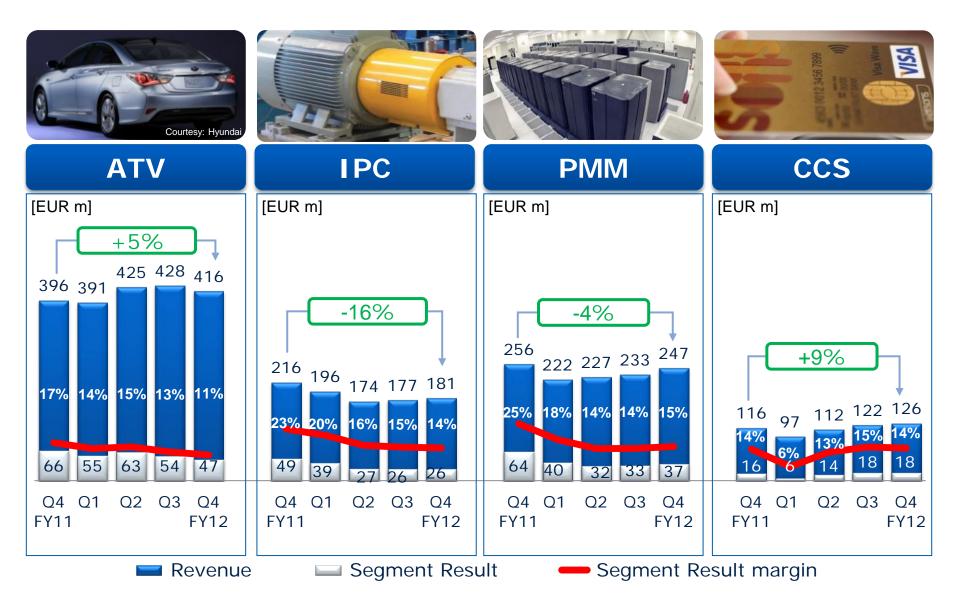
After Record Revenues in 2011 Sales during 2012 Stay Almost Flat





ATV Remains on High Level Steady Recovery in PMM



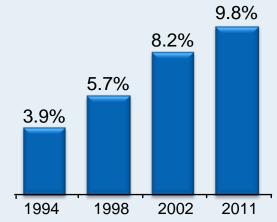


Automotive: Infineon Biggest Market Share Gainer Amongst All Players in 2011









Infineon

- strengthened world's #2 postion;
- rose from #8 to #4 position in Japan.

Europe

1.	Infineon	14.7%
2.	STM	11.3%
3.	Bosch	9.4%
4.	Freescale	8.7%
5.	NXP	8.2%
6.	Renesas	8.0%
7.	Tì 🙏 🗼	6.8%
8.	ON Semi	3.0%

APAC & others*

1.	STM	10.1%
2.	Infineon	9.0%
3.	Renesas	7.5%
4.	Freescale	7.4%
5.	NXP	7.3%
6.	Bosch	5.7%
7.	Toshiba	2.9%
8.	TI	2.6%

North America

1 .	Freescale	13.8%
2.	Infineon	8.5%
3.	STM	8.0%
4.	Renesas	7.5%
5.	NXP	6.7%
6.	TI	6.0%
7.	Bosch	3.7%
8.	ON	3.3%

Japan

Renesas	35.1%
Toshiba	13.0%
Fujitsu	3.9%
Infineon	3.8%
Rohm	3.6%
STM	3.6%
ON	3.1%
Sanken	2.9%
	Toshiba Fujitsu Infineon Rohm STM ON

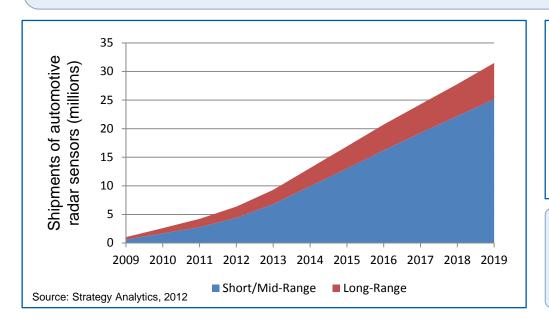
Source: Strategy Analytics, April 2012 * According to Strategy Analytics this ranking also includes Russia, South America, Australia and further countries.

Increasing Adoption of Infineon's 77 GHz SiGe Technology for Radar Applications



RASIC serves rapid growth in advanced driver assistance systems

- Infineon's Radar System IC (RASIC™) series consists of a group of highly-integrated functions for 77 GHz automotive radar sensors.
- With more than 1m devices shipped since 2009, Infineon is a market leader today and strengthens its future position with the recent release of a "77 GHz radar-in-package".
- Multiple design-wins have been recorded at major automotive suppliers in the USA, Europe and Asia.



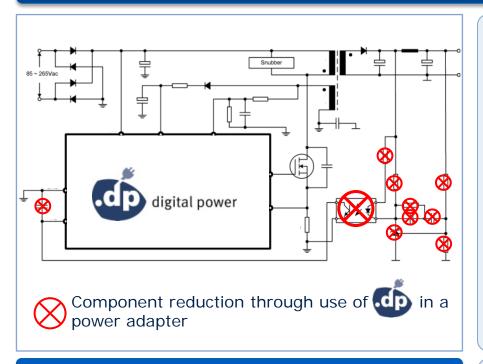


Bringing 77 GHz performance to the short- and mid-range market.

Infineon's Digital Power Management ICs Now Ramping for AC/DC Applications



Enabling high-efficiency AC/DC conversion while reducing system costs



- uses digital control algorithms allowing system complexity reduction and flexibility to adapt to rapidly-changing market requirements.
- is tailored to offer our customers best in both system cost and efficiency over all load conditions.

Target applications



- started volume shipments for power adapters.
- Design-in activities now ramping for LED lighting.

Integrity Guard has been nominated for the "German Future Prize 2012"



Integrity Guard - Security for the connected world



DEUTSCHER ZUKUNFTSPREIS

Preis des Bundespräsidenten für Technik und Innovation

Nominated 2012

Integrity Guard –
Security for the connected world

- Infineon's innovative Integrity Guard digital security technology has been nominated for the "German Future Prize 2012 - The Federal President`s Award for Innovation and Technology".
- This award recognizes outstanding technical and scientific innovations from Germany. Nomination alone is regarded as the highest commendation for technology and innovation in Germany.
- Integrity Guard is based on digital security and displays two revolutionary innovations:
 - The completely encrypted storage and processing of on-chip data combined with
 - two CPUs constantly checking each other; and a full digital error-detection system.

Guidance for Q1 FY13 and FY 2013



Outlook Q1 FY13* (compared to Q4 FY12)



Outlook FY 2013* (compared to FY 2012)



Revenue

Revenue to decline by low teens percentage.

Mid- to high-single digit percentage decline.

Segment Result Margin

Between 4 and 6 percent.

In the mid- to highsingle digits.

Investments in FY 2013

About EUR 400m.

D&A in FY 2013

About EUR 470m.

^{*} This outlook is based on an assumed Euro/US Dollar exchange rate of 1.25.



ENERGY EFFICIENCY MOBILITY SECURITY

Innovative semiconductor solutions for energy efficiency, mobility and security.

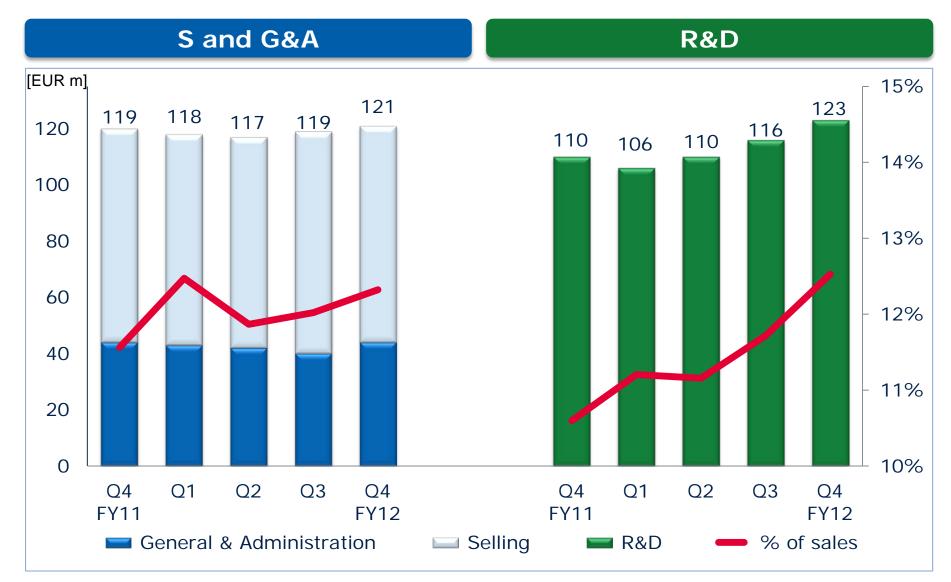






OpEx Development

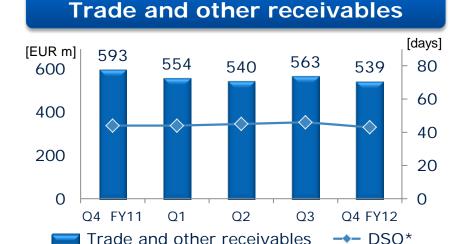




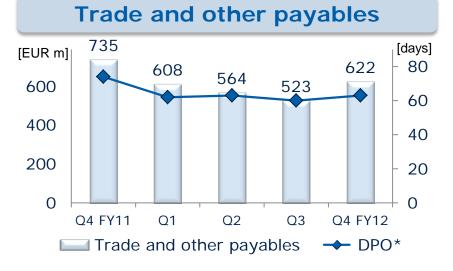
Working Capital









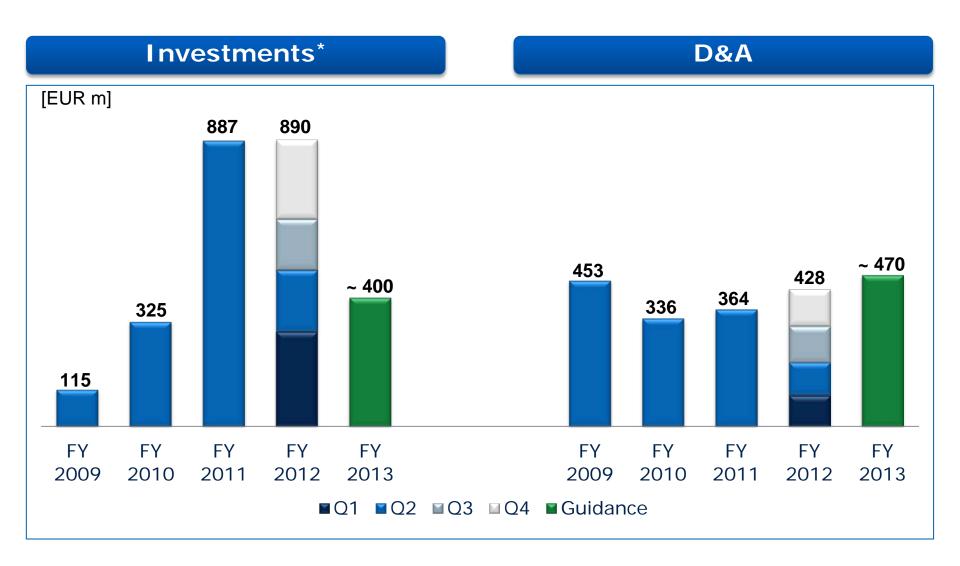


-800

^{*} For definition please see page 28 in appendix.

Investments in FY 2013 to Be Reduced Significantly

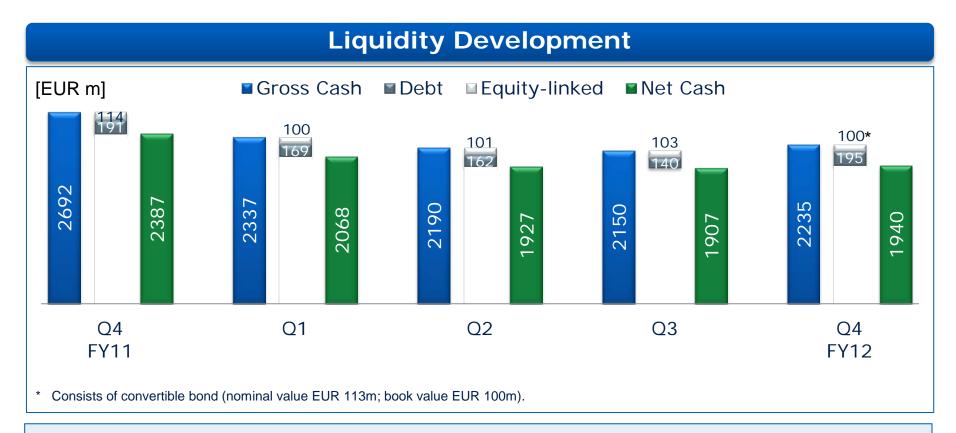




^{*} For definition please see page 28 in appendix.

Gross Cash and Net Cash Position Slightly Increased

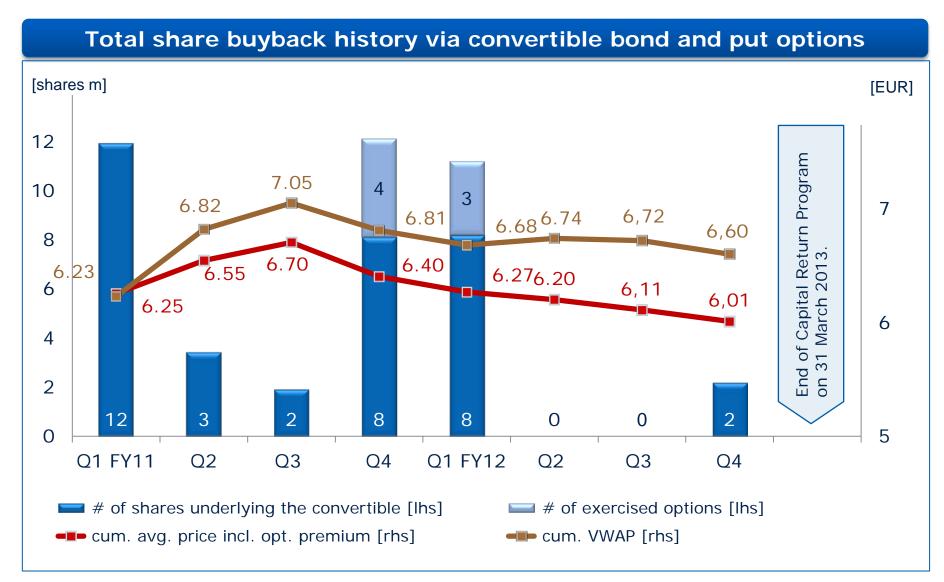




- Gross cash increased due to Free Cash Flow and an increase of debt of EUR 52m. Net cash impact correspondingly lower.
- Bought back EUR 5m nominal of convertible bond for EUR 12m.
- No buyback of shares during the quarter. But put options for 5m shares lapsed with EUR 2.2m premium received.

Average Price Per Underlying Share Below Volume Weighted Average Share Price

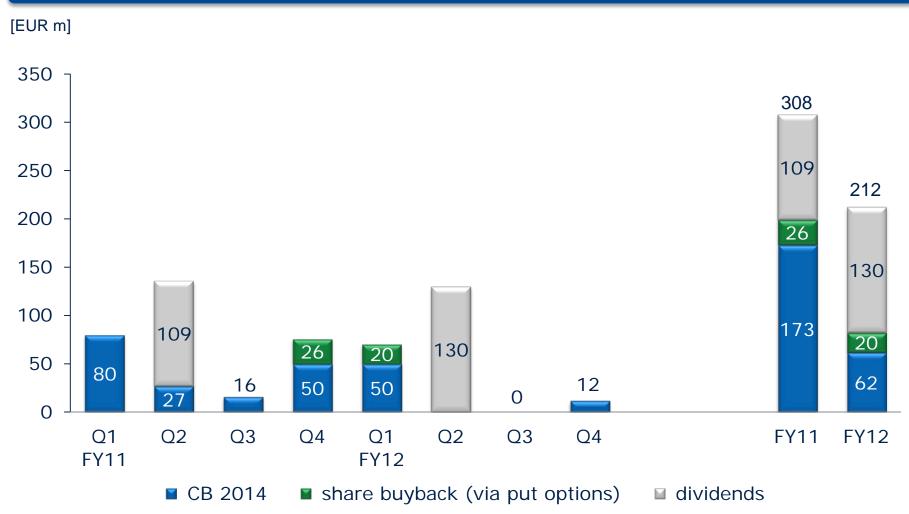






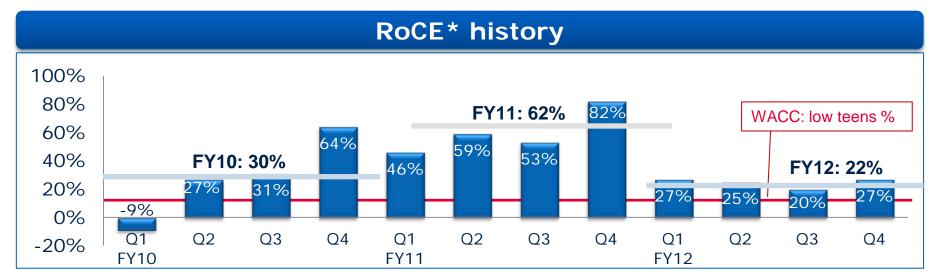






Value Creation of Infineon by Sustainably High RoCE Above WACC







^{*} For definition please see page 28 in appendix.

Notes



Investments =

'Purchase of property, plant and equipment'

+ 'Purchase of intangible assets and other assets' incl. capitalization of R&D expenses

Capital Employed =

'Total assets'

- 'Cash and cash equivalents'
- 'Financial investments'
- 'Assets classified as held for sale'
- ['Total Current liabilities'
- 'Short-term debt and current maturities of long-term debt'
- 'Liabilities classified as held for sale']

RoCE =

NOPAT / Capital Employed = ('Income from continuing operations'

- 'financial income'
- 'financial expense')

/ Capital Employed

Working Capital =

('Total current assets'

- 'Cash and cash equivalents'
- 'Financial investment'
- 'Assets classified as held for sale')
- ('Total current liabilities'
- 'Short term debt and current maturities of long-term debt'
- 'Liabilities classified as held for sale')

```
DOI (inventory days; quarter-to-date) = ('Net Inventories' / 'Cost of goods sold') * 90
```

DSO (days sales outstanding; quarter-to-date) = ('Trade accounts receivables (net)' / 'revenue') * 90

```
DPO (days payables outstanding; quarter-to-date) = ('Trade payables' / ['Cost of goods sold' + 'Purchase of property, plant and equipment']) * 90
```

Worldwide Frontend Production Sites



Regensburg



Employees: 1,081 202 Temps:

Capacity: 48k WSPM Technology: >200nm

Complexity: 16 mask layers

Products: Power

OOS 4% CCS 1% **IPC 1%** PMM 19%

ATV 74%

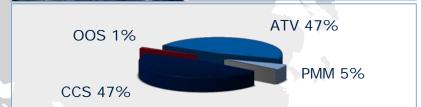
Dresden

Employees: 1,767 Temps: 168

Capacity: 45k WSPM Technology: >90nm

Complexity: 30 mask layers

Products: **CMOS**



Villach

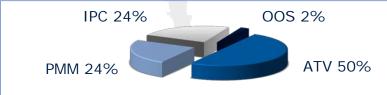


Employees: 1,669 Temps: 331

120k WSPM Capacity: Technology: >200nm

Complexity: 11 mask layers

Products: Power





Employees: 1161 Temps: 172

85k WSPM Capacity: Technology: >200nm

Complexity: 12 mask layers Products: Power, CMOS

ATV 38% PMM 35% CCS 9% **IPC 18%**

Note: As of September 2012.

WSPM = Wafer Starts Per Month (200mm equivalent), typical technology.

Worldwide Backend Production Sites



Morgan Hill, USA



Employees: 121

Competence center RF power

Warstein, Germany



Employees: 852

High power, R&D

Cegléd, Hungary



Employees: 531

High power

Regensburg, Germany



Employees: 779

Sensors, chip card, power, wafer level, R&D

Wuxi, China



Employees: 1,666

Chip card, discretes

Malacca, Malaysia



Employees: 6,828

Power, discretes, sensors, logic, R&D

Singapore



Employees: 1,203

Tester pool, R&D

Batam, Indonesia



Employees: 2,283

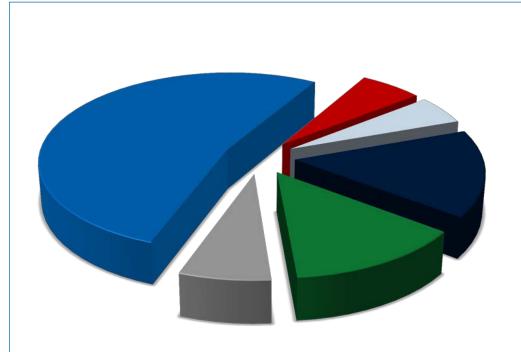
Power leadframe

Note: As of September 2012.

Investments Driven by Capacity Additions and Maintenance



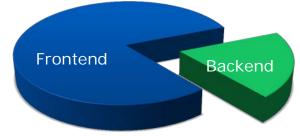
Breakdown of total investments in FY12 of EUR 890m



- Capacity
- **■** Quality
- Intangible assets, capitalized R&D

- Innovation
- Maintenance / facility
- Others





Infineon Has a Long Track Record in Responsibility and Sustainability



UN Global Compact Initiative

As one of the first semiconductor companies worldwide, Infineon joined the Global Compact Initiative of the United Nations in 2004.

Dow Jones Sustainability Index



Infineon is currently Europe's one and only semiconductor company member in the Dow Jones Sustainability Indexes.

Certifications



Based on our efforts for resources management, safety and health standards, Infineon received the EN ISO 14001 and OHSAS 18001 multi-site certification.

Financial Calendar



Date	Location	Event
27-28 Nov 2012	Scottsdale, AZ	Credit Suisse Technology Conference
06 Dec 2012	London	Natixis Payment Revolution Conference
31 Jan 2013*		Q1 FY13 Results
28 Feb 2013	Munich	Annual General Meeting
02 May 2013*		Q2 FY13 Results
30 Jul 2013*		Q3 FY13 Results
12 Nov 2013*		Q4 FY13 and FY 2013 Results

^{*} provisional

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